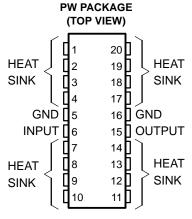
SLVS067H - MARCH 1992 - REVISED MAY 2003

- Fixed 3.3-V Output
- ±1% Maximum Output Voltage Tolerance at T_J = 25°C
- 500-mV Maximum Dropout Voltage at 500 mA
- 500-mA Dropout Current
- ±2% Absolute Output Voltage Variation
- Internal Overcurrent Limiting
- Internal Thermal-Overload Protection
- Internal Overvoltage Protection

description/ordering information

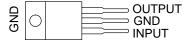
The TLV2217-33 is a low-dropout 3.3-V fixed-voltage regulator. The regulator is capable of sourcing 500 mA of current with an input-output differential of 0.5 V, or less. The TLV2217-33 provides internal overcurrent limiting, thermal-overload protection, and overvoltage protection.

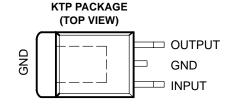
The 0.5-V dropout for the TLV2217-33 makes it ideal for battery applications in 3.3-V logic systems. For example, battery input voltage to the regulator can drop as low as 3.8 V, and the TLV2217-33 can continue to regulate the system. For higher voltage systems, the TLV2217-33 can be operated with a continuous input voltage of 12 V.



HEAT SINK – These terminals have an internal resistive connection to ground and should be grounded or electrically isolated.







ORDERING INFORMATION

TJ	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	POWER-FLEX (KTP)	Reel of 3000	TLV2217-33KTPR	2217-33	
0°C to 125°C	TO-220 (KC)	Tube of 50	TLV2217-33KC	TLV2217-33	
	TSSOP (PW)	Reel of 2000	TLV2217-33CPWR	2217-33	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TLV2217-33 LOW-DROPOUT 3.3-V FIXED-VOLTAGE REGULATORS

SLVS067H - MARCH 1992 - REVISED MAY 2003

absolute maximum ratings over operating virtual junction temperature range (unless otherwise noted)†

Continuous input voltage, VI		. 16 V
Operating virtual junction temperature, T _J		150°C
Storage temperature range, T _{stg}	–65°C to	150°C

package thermal data (see Note 1)

PACKAGE	BOARD	θЈС	$^{ heta}$ JA
POWER-FLEX (KTP)	High K, JESD 51-5	19°C/W	28°C/W
TO-220 (KC)	High K, JESD 51-5	3°C/W	19°C/W
TSSOP (PW)	High K, JESD 51-7	32°C/W	83°C/W

NOTE 1: Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability. Due to variation in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.

recommended operating conditions

		MIN	MAX	UNIT
٧ı	Input voltage	3.8	12	V
lo	Output current	0	500	mA
TJ	Operating virtual junction temperature range	0	125	°C

electrical characteristics at V_I = 4.5 V, I_O = 500 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TTOT OCUPITIONS!		TLV2217-33			UNIT		
PARAMETER	TEST CONDITIONS‡			MIN	TYP	MAX	UNIT	
Output voltage	$I_{O} = 20$ mA to 500 mA, $V_{I} = 3.8$ V to 5.5 V	\/. 2.9.\/ to F.F.\/	T _J = 25°C	3.267	3.30	3.333	V	
		V = 3.6 V to 5.5 V	T _J = 0°C to 125°C	3.234		3.366		
Input voltage regulation	V _I = 3.8 V to 5.5 V	V _I = 3.8 V to 5.5 V			5	15	mV	
Ripple rejection	f = 120 Hz,	V _{ripple} = 1 V _{PP}			-62		dB	
Output voltage regulation	I _O = 20 mA to 500 mA				5	30	mV	
Output noise voltage	f = 10 Hz to 100 kHz				500		μV	
Dropout voltage	I _O = 250 mA					400	mV	
	I _O = 500 mA					500	IIIV	
Bias current	IO = 0				2	5	mA mA	
	I _O = 500 mA				19	49		

[‡] Pulse-testing techniques are used to maintain the virtual junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1-μF capacitor across the input and a 22-μF tantalum capacitor with equivalent series resistance of 1.5 Ω on the output.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TLV2217-33 LOW-DROPOUT 3.3-V FIXED-VOLTAGE REGULATORS

SLVS067H - MARCH 1992 - REVISED MAY 2003

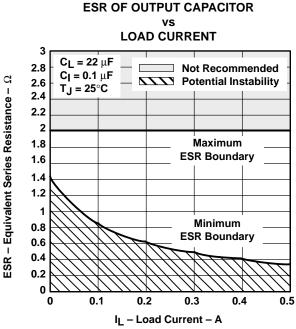
electrical characteristics at V_I = 4.5 \underline{V} , I_O = 500 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		TLV2217-33Y			UNIT	
FARAMETER			MIN	TYP	MAX	UNIT	
Output voltage	$I_O = 20 \text{ mA to } 500 \text{ mA},$	$V_I = 3.8 \text{ V to } 5.5 \text{ V}$	3.267	3.30	3.333	V	
Input voltage regulation	V _I = 3.8 V to 5.5 V			5	15	mV	
Ripple rejection	f = 120 Hz,	V _{ripple} = 1 V _{PP}		-62		dB	
Output voltage regulation	I _O = 20 mA to 500 mA			5	30	mV	
Output noise voltage	f = 10 Hz to 100 kHz			500		μV	
Dropout voltage	I _O = 250 mA				400	mV	
Dropout voltage	I _O = 500 mA				500	IIIV	
Bias current	I _O = 0			2	5	m /\	
Dias current	I _O = 500 mA			19	49	mA	

[†] Pulse-testing techniques are used to maintain the virtual junction temperature as close to the ambient temperature as possible. Thermal effects must be taken into account separately. All characteristics are measured with a 0.1- μ F capacitor across the input and a 22- μ F tantalum capacitor with equivalent series resistance of $1.5~\Omega$ on the output.

COMPENSATION-CAPACITOR SELECTION INFORMATION

The TLV2217-33 is a low-dropout regulator. This means that the capacitance loading is important to the performance of the regulator because it is a vital part of the control loop. The capacitor value and the equivalent series resistance (ESR) both affect the control loop and must be defined for the load range and the temperature range. Figures 1 and 2 can be used to establish the capacitance value and ESR range for best regulator performance.



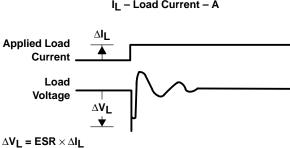


Figure 1

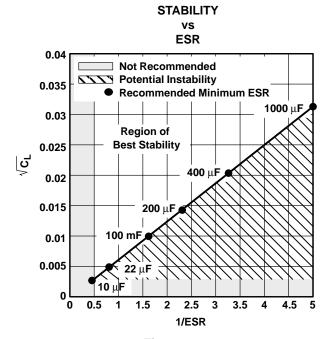


Figure 2



APPLICATION INFORMATION

application schematic

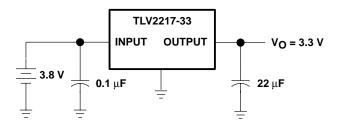
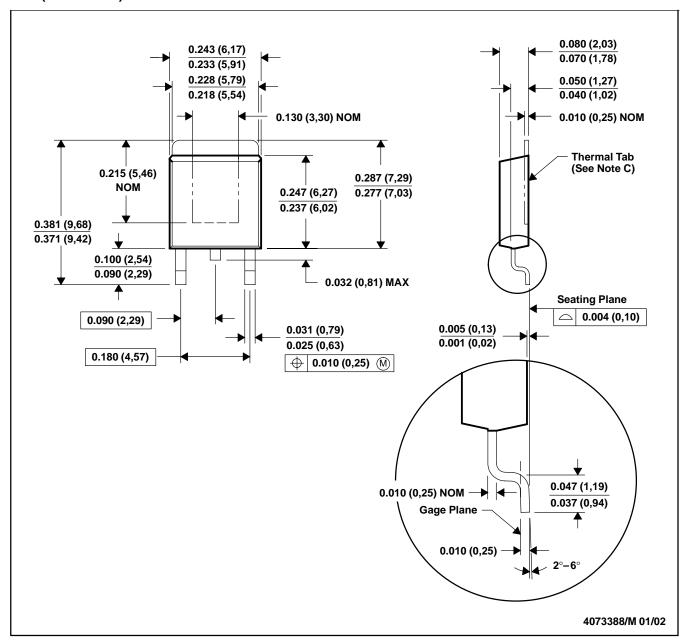


Figure 3

KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

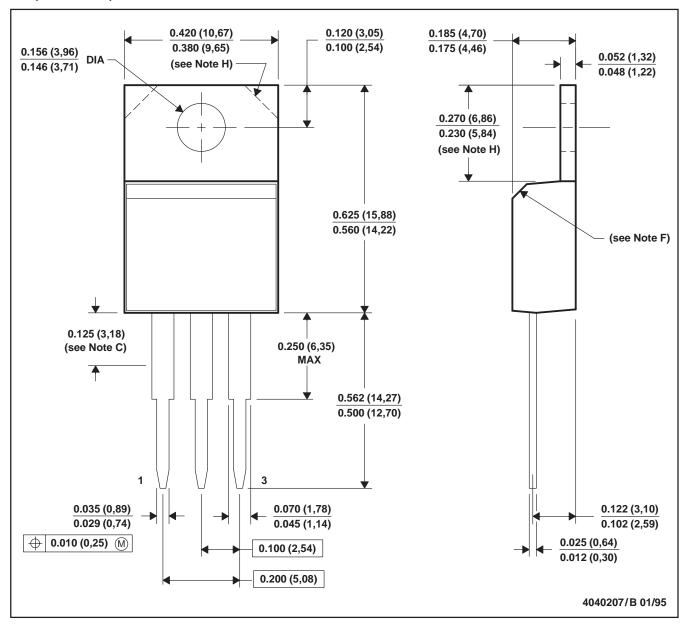
- B. This drawing is subject to change without notice.
- C. The center lead is in electrical contact with the thermal tab.
- D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
- E. Falls within JEDEC TO-252 variation AC.

PowerFLEX is a trademark of Texas Instruments.



KC (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

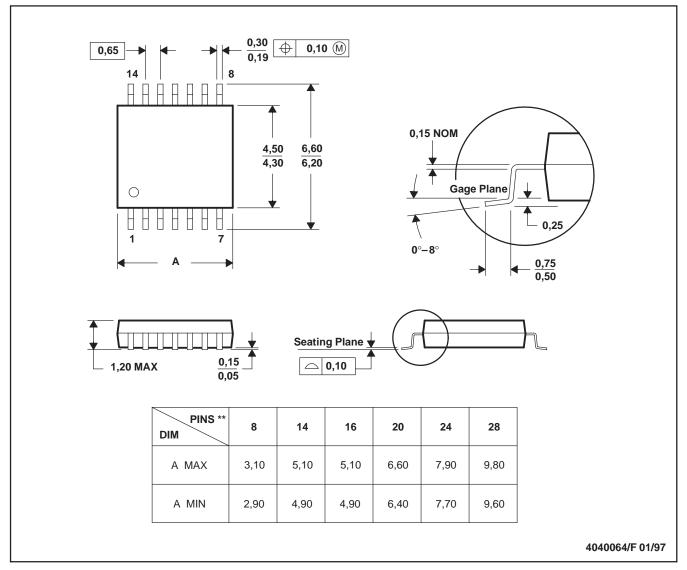
- B. This drawing is subject to change without notice.
- C. Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- F. The chamfer is optional.
- G. Falls within JEDEC TO-220AB
- H. Tab contour optional within these dimensions



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third—party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

Copyright © 2003, Texas Instruments Incorporated